20 LASER WAFER PROCESSING

28 PLANAR LIGHT GUIDING CIRCUIT (PLC) WAFER PROCESSING

22 FORM STUDS

30 ETCH CAVITY

24 FORM FIRST PATTERN OF MARKS

32 FORM SECOND PATTERN OF MARKS

26 SEPARATE WAFER INTO DIES

Applicant(s): Kristian Blidegn ACCURATE POSITIONING OF COMPONENTS OF AN

Page 1 of 7

Matter No.: 14069-004001

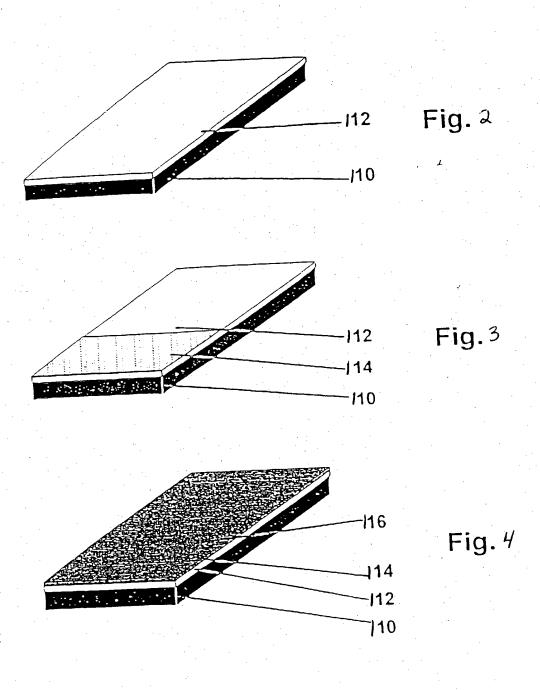
34 FLIP-CHIP THE LASER DIES(S) ONTO THE PLC

36 POSITION THE LASER

38 CHECK POSITIONING USING BEAT FREQUENCY TECHNIQUE

40 FIX THE LASER IN POSITION

Matter No.: 14069-004001 Page 2 of 7
Applicant(s): Kristian Blidegn
ACCURATE POSITIONING OF COMPONENTS OF AN
OPTICAL ASSEMBLY



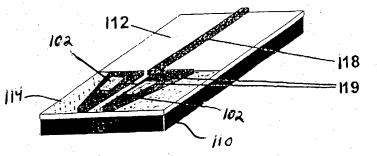


Fig. 5

Matter No.: 14069-004001 Page Applicant(s): Kristian Blidegn ACCURATE POSITIONING OF COMPONENTS OF AN OPTICAL ASSEMBLY

Page 3 of 7

112-102 118 -119

110

Fig. 6

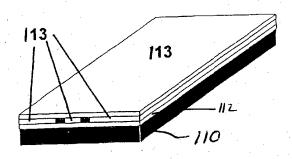


Fig. 7

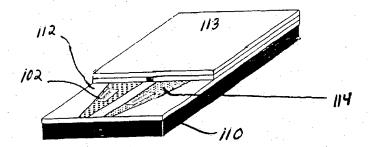


Fig. 8

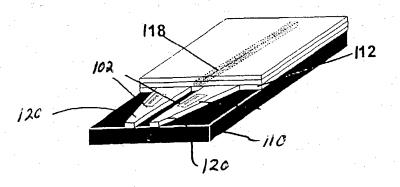
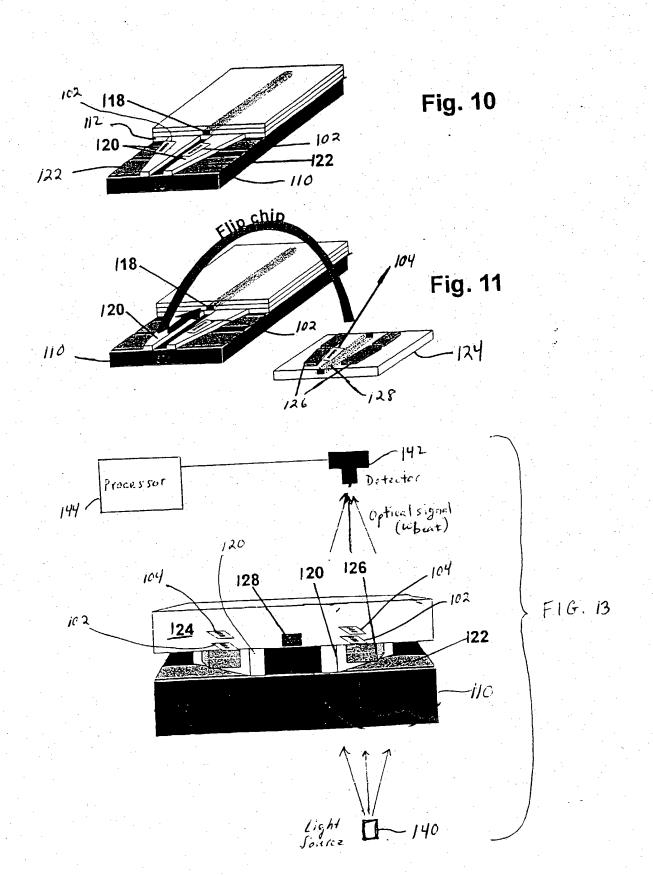


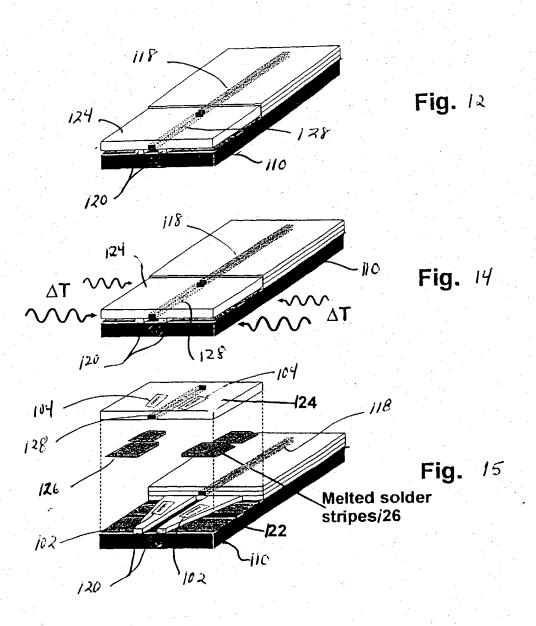
Fig. 9

Matter No.: 14069-004001 Page 4 of 7
Applicant(s): Kristian Blidegn
ACCURATE POSITIONING OF COMPONENTS OF AN
OPTICAL ASSEMBLY

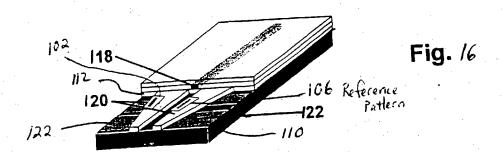


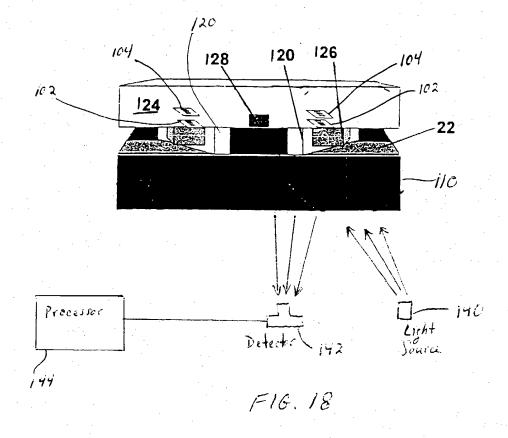
Page 5 of 7

Matter No.: 14069-004001 Page Applicant(s): Kristian Blidegn ACCURATE POSITIONING OF COMPONENTS OF AN OPTICAL ASSEMBLY



Matter No.: 14069-004001 Page 6 of 7
Applicant(s): Kristian Blidegn
ACCURATE POSITIONING OF COMPONENTS OF AN
OPTICAL ASSEMBLY







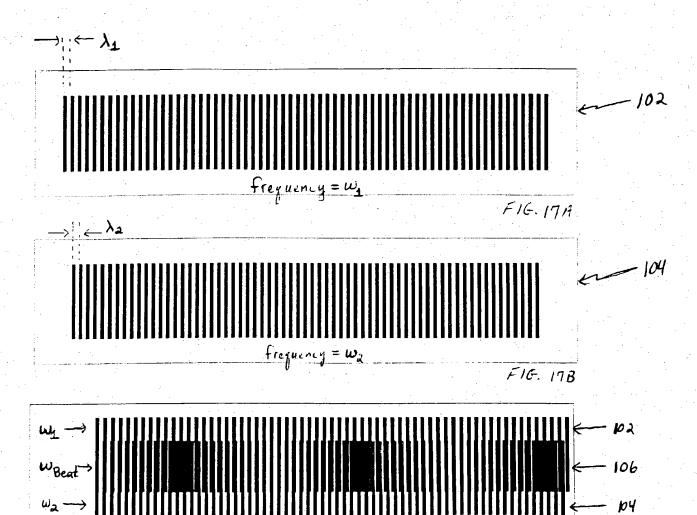


FIG. MC